

## **IN THE CLAIMS:**

### **Amendments to the Claims**

Please amend claims 1, 2, 8 and 13 and add the new claims as shown below.

### **Listing of Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A multilayer electronic part having a surface electrode, an internal electrode and a back electrode, wherein alternate ones of the electrodes along the thickness of the multilayer are electrically connected to each other thereby to constitute two electrode groups, the multilayer electronic part having two electrode portions for external connection which are electrically connected with said two electrode groups, characterized in that said two electrode groups are electrically connected on one side surface of said multilayer electronic part, said one side surface being partially formed of respective one side edges of said surface electrode, said internal electrode and said back electrode.

2. (currently amended) A multilayer electronic part as described in Claim 1, characterized in that said multilayer electronic part is configured with a chip-like element and a flexible board attached to one side surface of said chip-like element forming a portion of said one side surface of said multilayer electronic part, and alternate ones of the electrodes along the thickness of the multilayer of said chip-like element are connected to each other by an electrode pattern of said flexible board thereby to constitute said two electrode groups.

3. (original) A multilayer electronic part as described in Claim 2, characterized in that an insulative adhesive is filled in the minuscule gap between said chip-like element and said flexible board.

4. (original) A multilayer electronic part as described in Claim 2, characterized in that said two electrode portions for external connection are formed on one side surface of said chip-like element or the extension of said one side surface.

5. (original) A multilayer electronic part as described in Claim 4, characterized in that said two electrode portions for external connection are formed of the end portions of a pair of said electrode patterns of said flexible board.

6. (original) A multilayer electronic part as described in Claim 2, characterized in that each of said electrodes of said chip-like element and said electrode pattern of said flexible board are connected to each other by a thick film conductive paste or a solder or an anisotropic conductive sheet.

7. (original) A multilayer electronic part as described in Claim 2, characterized in that an insulation pattern for cutting off the conduction between adjacent electrodes along the thickness of the multilayer of said chip-like element is formed on said chip-like element or said flexible board.

8. (currently amended) A method of manufacturing a multilayer electronic part configured with a chip-like element having a surface electrode, an internal electrode and a back electrode and a flexible board attached to one side surface of said chip-like element, wherein one side edge of alternate ones of the electrodes

along the thickness of a multilayer of said chip-like element forming a portion of said one side surface of said chip-like element are electrically connected to each other by an electrode pattern of said flexible board thereby to constitute two electrode groups, and two electrode portions for external connection which are electrically connected with said two electrode groups are formed of the electrode pattern of said flexible board or a conductive portion connected to said electrode pattern;

said method comprising the steps of cutting out a bar-shaped subbase member as wide as one chip from the base member of said chip-like element, electrically connecting alternate ones of the one side edge of the electrodes along the thickness of said bar-shaped subbase member with each electrode pattern of said flexible board base member including a multiplicity of electrode pattern pairs by fixedly connecting said flexible board base member to the longitudinal side surface of said bar-shaped base member, and cutting out each multilayer electronic part from an integrated member of said bar-shaped subbase member and said flexible board base member.

9. (original) A method of manufacturing a multilayer electronic part as described in Claim 8, characterized in that said manufacturing steps are carried out with other members attached to the upper and lower surfaces of the base member of said chip-like element.

10. (original) A method of manufacturing a multilayer electronic part as described in Claim 8, characterized in that an insulative adhesive is filled in the minuscule gap between said bar-shaped subbase member and the base member of said flexible board with said bar-shaped base member and said base member of said flexible board integrated with each other.

11. (original) A method of manufacturing a multilayer electronic part as described in Claim 8, characterized in that each of said electrodes exposed to the long side surface of said bar-shaped subbase member is plated for connection assistance.

12. (original) A method of manufacturing a multilayer electronic part as described in Claim 8, characterized in that an insulative pattern for cutting off the conduction between the adjacent electrodes along the thickness of the multilayer of said bar-shaped subbase member is formed on said flexible board.

13. (currently amended) A two-dimensionally arrayed element packaging structure characterized in that a plurality of electronic parts are integrated by being arranged in columns and rows in a two-dimensional array as a module, wherein each of said electronic parts is configured with a chip-like element having at least a surface electrode and a back electrode and a flexible board attached to one side surface of said chip-like element, one side edge of the surface electrode and one side edge of the back electrode of said chip-like element forming a portion of said one side surface of said chip-like element are electrically connected to a corresponding electrode pattern of said flexible board, and two electrode portions for external connection which are electrically connected to said surface electrode and said back electrode are formed of the electrode pattern of said flexible board or a conductive portion connected with said electrode pattern.

14. (original) A two-dimensionally arrayed element packaging structure as described in Claim 13, characterized in that each of said electrodes of said chip-like element and said electrode pattern of said flexible board are connected to each other by a thick-film conductive paste or a solder or an anisotropic conductive sheet.

15. (original) A two-dimensionally arrayed element packaging structure as described in Claim 13, characterized in that said chip-like element is a single-layer structured element having only a surface electrode and a back electrode or a multilayer structured element having a surface electrode, an internal electrode and a back electrode.

16. (original) A method of manufacturing a two-dimensionally arrayed element packaging structure, characterized in that only a plurality of acceptable ones of the multilayer electronic parts as described in any one of Claims 1 to 7 or only a plurality of acceptable ones of the multilayer electronic parts manufactured by the manufacturing method as described in any one of Claims 8 to 12 are integrated by being aligned in columns and rows thereby to complete a two-dimensionally arrayed module.

17. (new) A multilayer electronic part as described in claim 1, wherein each of the electrodes has the same planar shape and area, and the electrical connection of said electrodes of said multilayer electronic part is effected only on said one side surface.

18. (new) A multilayer electronic part as described in claim 17, wherein said electrodes form a portion of a stacked transducer, and the electrical connection of said electrodes is effected only at said one surface which is an outer surface of the stacked transducer.

19. (new) A method of manufacturing a multilayer electronic part as described in claim 8, wherein each of said electrodes has the same planar shape

and area, and the electrical connection of said electrodes of said multilayer electronic part is effected only on said one side surface.

20. (new) A method of manufacturing a multilayer electronic part as described in claim 19, wherein said electrodes form a portion of a stacked transducer, and the electrical connection of said electrodes is effected only at said one surface which is an outer surface of the stacked transducer.

21. (new) A two-dimensionally arrayed element packaging structure as described in claim 13, wherein each of said electrodes has the same planar shape and area, and the electrical connection of said electrodes of said multilayer electronic part is effected only on said one side surface.

22. (new) A two-dimensionally arrayed element packaging structure as described in claim 13, wherein said electrodes form a portion of a stacked transducer, and the electrical connection of said electrodes is effected only at said one surface which is an outer surface of the stacked transducer.